

## DESCRIPTION

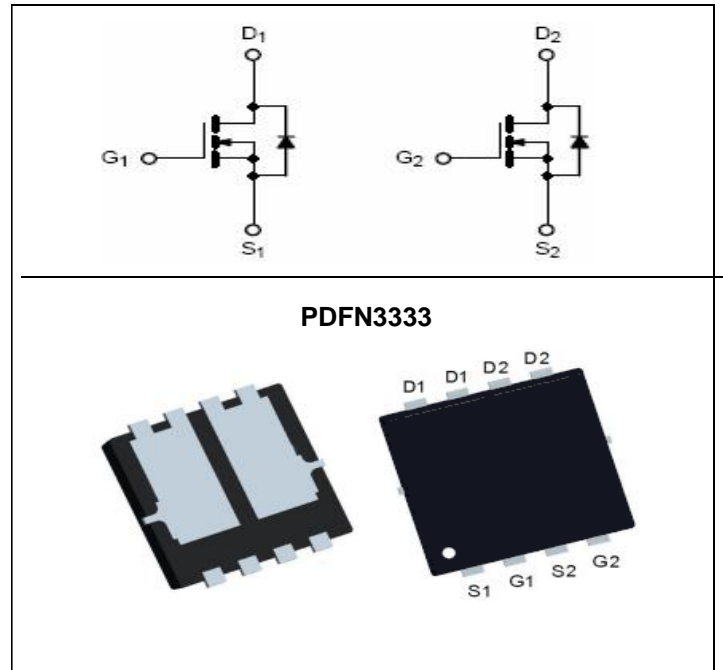
The 3622DE uses advanced trench technology to provide excellent RDS(ON) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

## GENERAL FEATURES

- RDS(ON) <10 mΩ @ VGS=10V  
RDS(ON) <13 mΩ @ VGS=4.5V
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

## Application

- PWM applications
- Load switch
- Power management



### ■ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V <sub>DS</sub>	30	V
Gate-source Voltage		V <sub>GS</sub>	±20	V
Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	35	A
	T <sub>C</sub> =100°C		22	
Pulsed Drain Current <sup>A</sup>		I <sub>DM</sub>	140	A
Total Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	20	W
	T <sub>C</sub> =100°C		15	W
Single Pulse Avalanche Energy <sup>B</sup>		E <sub>AS</sub>	16	mJ
Thermal Resistance Junction-to-Case <sup>C</sup>		R <sub>θJC</sub>	45	°C/W
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55~+155	°C

**ELECTRICAL CHARACTERISTICS** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	$T_J=25^\circ\text{C}$		1	$\mu A$
			$T_J=55^\circ\text{C}$		5	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=15A$		8.0	10	m $\Omega$
		$V_{GS}=4.5V, I_D=15A$		10	13	
Diode Forward Voltage	$V_{SD}$	$I_S=15A, V_{GS}=0V$		0.85	1.2	V
Maximum Body-Diode Continuous Current	$I_S$				30	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$		1020		$\mu F$
Output Capacitance	$C_{oss}$			225		
Reverse Transfer Capacitance	$C_{rss}$			126		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V, V_{DS}=15V, I_D=30A$		28		nC
Gate-Source Charge	$Q_{gs}$			7		
Gate-Drain Charge	$Q_{gd}$			5		
Reverse Recovery Charge	$Q_{rr}$	$I_F=15A, di/dt=100A/\mu s$		25		nC
Reverse Recovery Time	$t_{rr}$			26		
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=20V, I_D=2A, R_L=1\Omega, R_{GEN}=3\Omega$		8		ns
Turn-on Rise Time	$t_{tr}$			15		
Turn-off Delay Time	$t_{D(off)}$			27		
Turn-off fall Time	$t_{tf}$			7		

A. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$ .

B.  $T_J=25^\circ\text{C}$ ,  $V_{DD}=20V$ ,  $V_G=10V$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$

C.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design, while  $R_{\theta JA}$  is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

## ■ Typical Performance Characteristics

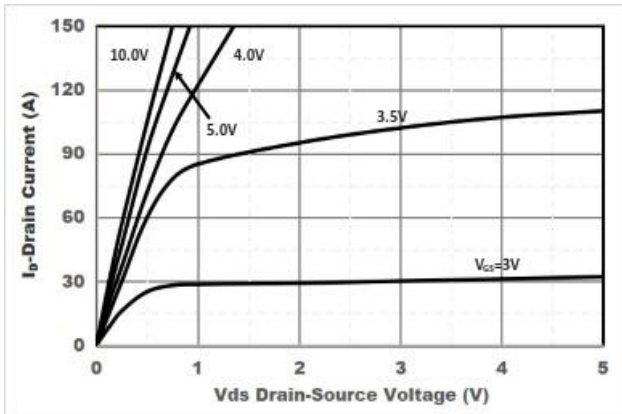


Figure1. Output Characteristics

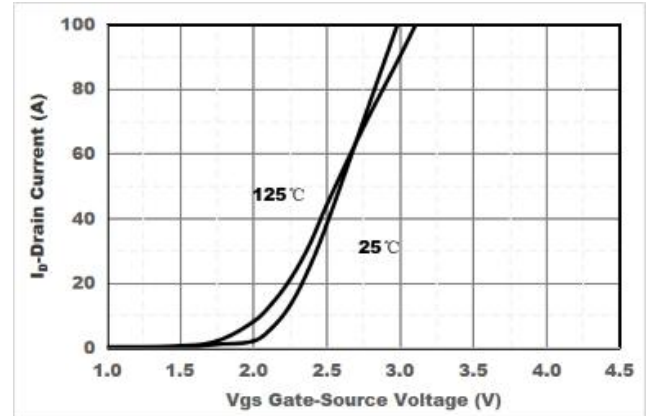


Figure2. Transfer Characteristics

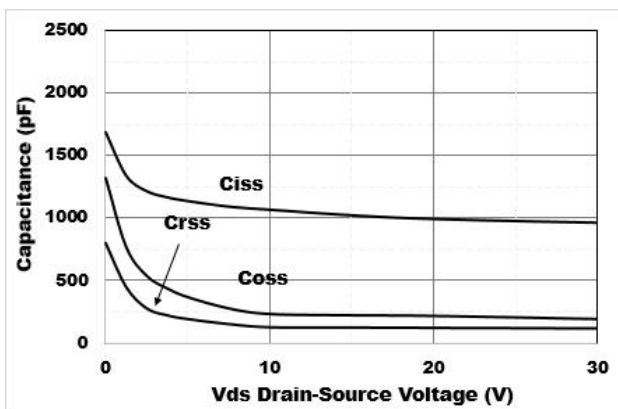


Figure3. Capacitance Characteristics

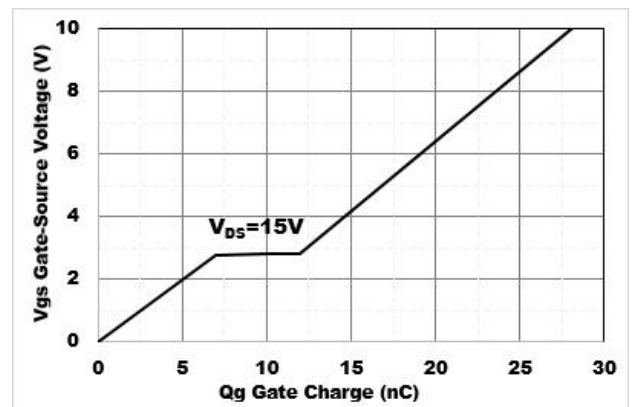


Figure4. Gate Charge

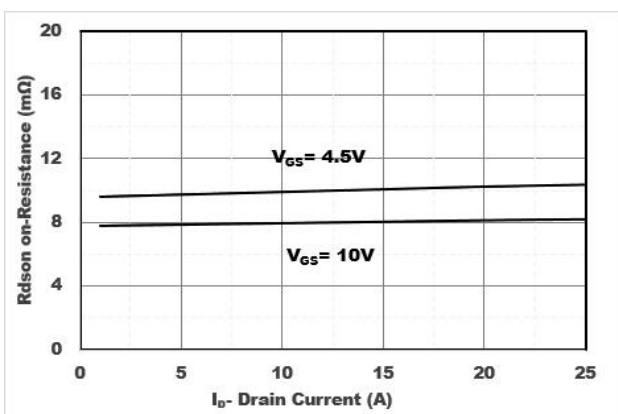


Figure5. Drain-Source on Resistance

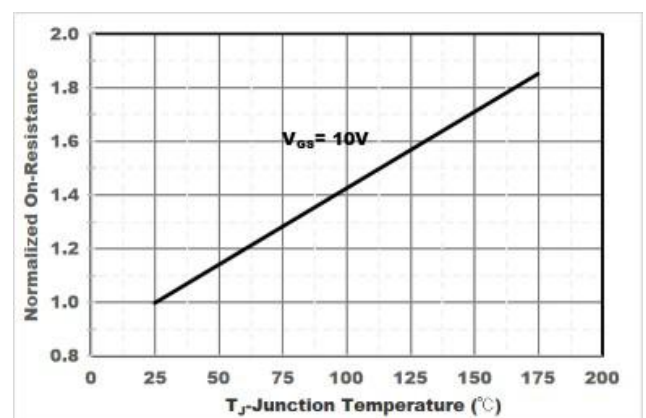


Figure6. Drain-Source on Resistance

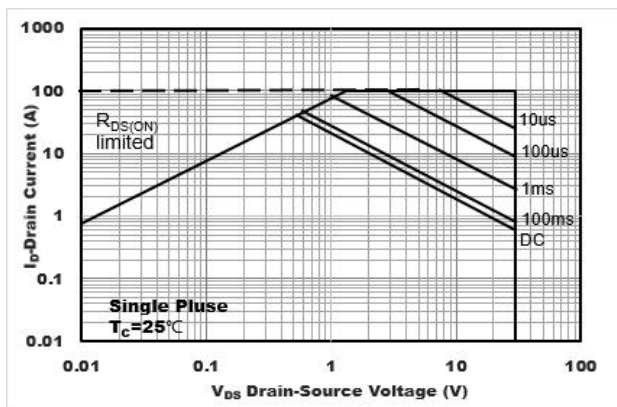


Figure7. Safe Operation Area

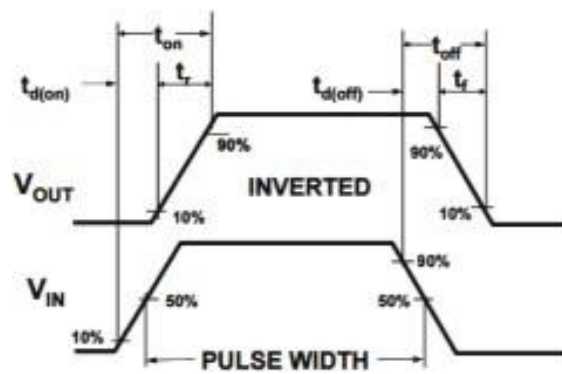
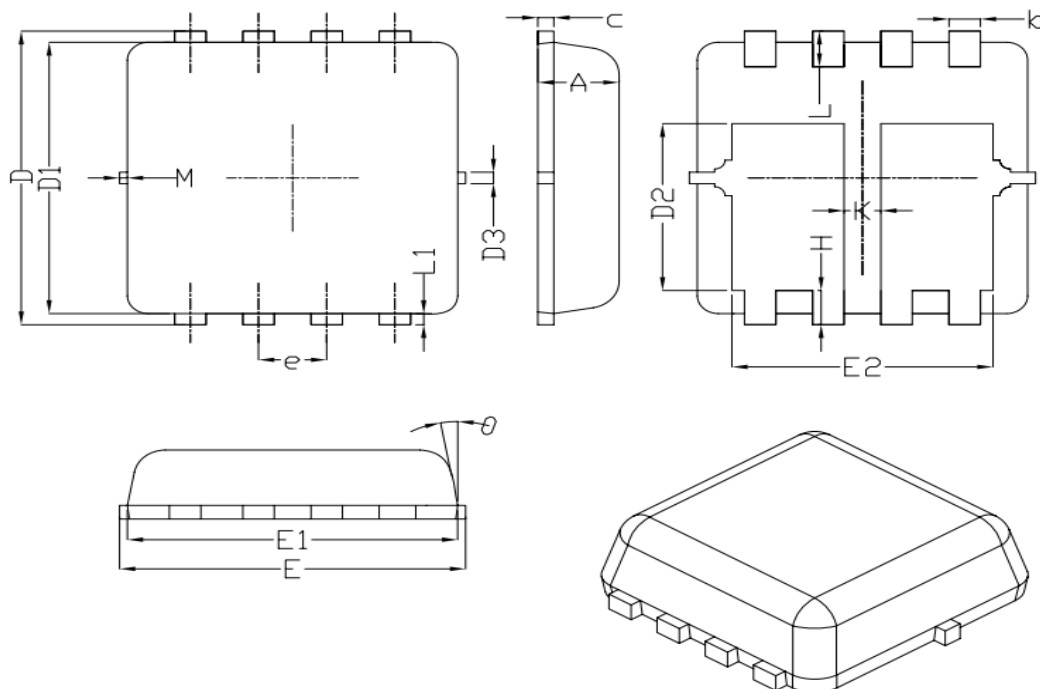


Figure8. Switching wave

## Package Information



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	--	0.13	--
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65 BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	--	0.13	--
K	0.30	--	--
$\theta$	--	10°	12°
M	*	*	0.15
* Not Specified			